



Material Composition Sheet

Product: GS1559-CB
 Package Type: BGA-100 Pin
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		12.85	Al	0.08	0.62	6226
			Si	12.77	99.37	993774
			Sub-total:	12.85	99.99	1000000
Die Attach	2100A	2.51	Ag	1.93	76.89	768924
			Epoxy Resin	0.58	23.10	231076
			Sub-total:	2.51	99.99	1000000
Molding Compound	KE-G1270	237.39	Carbon Black	1.19	0.50	5013
			Epoxy Resin	14.24	5.99	59986
			Phenol Resin	13.06	5.50	55015
			Silica Fused	208.90	87.99	879987
			Sub-total:	237.39	99.98	1000001
Solder Balls		50.43	Pb	18.66	37.00	370018
			Sn	31.77	62.99	629982
			Sub-total:	50.43	99.99	1000000
Substrate	BT HL842	138.25	Acrylic	12.72	9.20	92007
			Au	0.68	0.49	4919
			Bisphenol	20.71	14.98	149801
			Br	0.09	0.06	651
			Cu	54.38	39.33	393345
			Epoxy	8.49	6.14	61410
			Ni	1.92	1.38	13888
			SiO2	14.50	10.48	104882
Triazol	24.76	17.90	179096			
Sub-total:	138.25	99.96	999999			
Wire	MGFL1-B	2.33	Au	2.33	100.00	1000000
			Sub-total:	2.33	100.00	1000000
Total:		443.76				

GENNUM CORPORATION

Mailing Address: P.O. Box 489, Stn. A, Burlington, Ontario, Canada L7R 3Y3
 Shipping Address: 970 Fraser Drive, Burlington, Ontario, Canada L7L 5P5
 Tel. +1 (905) 632-2996 Fax. +1 (905) 632-5946

www.gennum.com

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